

SID

Factory: Rot am See

Article:

ML8

Provided:

Customer:

Date:

24.04.2026

WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-009my 330x490mm	50201012	9	VS	1	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		2	
		35	L2		
C-RS-FR4-ML-0.305mm-035+035-TG150-HF-...	50203020	305		3	A01
		35	L3		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		4	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		5	
		35	L4		
C-RS-FR4-ML-0.305mm-035+035-TG150-HF-...	50203020	305		6	A02
		35	L5		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		7	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		8	
		35	L6		
C-RS-FR4-ML-0.305mm-035+035-TG150-HF-...	50203020	305		9	A03
		35	L7		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	60		10	
A-RS Kupferfolie-009my 330x490mm	50201012	9	RS	11	

Thickness after Pressing

B00:

1490 µm

Tol+:

160 µm

Tol-:

160 µm

Dmax:

1650 µm

Dmin:

1330 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1600 µm

Tol+:

160 µm

Tol-:

160 µm

Dmax:

1760 µm

Dmin:

1440 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

1513 µm

Version 1.2.20.35

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